IN THE CLAIMS:

Revise the claims as follows:

1-17. (Cancelled).

18. (Currently Amended) A surface mount composite electronic component, comprising a circuit element formed on a pair of opposed surfaces of an insulating substrate composed of a hexahedron, comprising electrodes formed on the pair of opposed surfaces of the insulating substrate that make up the circuit element which also function as external terminals formed on the pair of opposed surfaces of the insulating substrate.

19. (Previously Presented) The surface mount composite electronic component according to claim 18, wherein the circuit element is composed of electrodes as well as resistors or dielectrics that contact said electrodes, a nickel plate layer and a solder plate layer laid down, in that order, on the surfaces of external terminal areas of said electrodes.

20. (Previously Presented) The surface mount composite electronic component according to claim 18, wherein one surface of the insulating substrate is substantially perpendicular to an adjacent surface.

21. (Previously Presented) The surface mount composite electronic component according to claim 18, having an area in which no electrodes are present on an edge portion of the surface of the insulating substrate on which said external terminals are present, disposed

perpendicular to a straight line connecting a pair of external terminals electrically connected to one circuit element.

22. (Previously Presented) The surface mount composite electronic component according to claim 18, having an area in which the electrodes and the resistor overlap and contact each other on the surface of the insulating substrate, the resistor disposed on the insulating substrate in said area, and further, the electrodes laid on the resistor.

23. (Previously Presented) The surface mount composite electronic component according to claim 18, wherein a relation between an insulating substrate dimension (L) in a direction of flow of electric current of the circuit element of the insulating substrate surface on which circuit elements are formed, an insulating substrate dimension (T) perpendicular to L, and a distance (W) between surfaces of the insulating substrate on which the circuit elements are formed is $L \geq W > T$.

24. (Previously Presented) The surface mount composite electronic component according to claim 18, wherein the electrodes that also function as external terminals are also present on a surface of the insulating substrate adjacent to the surface of the insulating substrate on which the circuit elements are present.

25. (Currently Amended) A surface mount composite electronic component, comprising:

a pair of first electrodes disposed on both ends of a front surface of an insulating substrate composed of a hexahedron and a first shared electrode disposed on the front surface of the insulating substrate between and separate from said first electrodes;

a pair of second electrodes disposed on a rear surface of the insulating substrate opposite the first electrodes and a second shared electrode disposed on the rear surface of the insulating substrate between and separate from said second electrodes;

two first resistors disposed on the front surface of the insulating substrate so as to contact the first pair of electrodes and the first shared electrode; and

two second resistors disposed on the rear surface of the insulating substrate so as to contact the second pair of electrodes and the second shared electrode.

26. (Previously Presented) The surface mount composite electronic component according to claim 25, wherein the number of external terminals is six.

27. (Previously Presented) The surface mount composite electronic component according to claim 25, wherein the circuit element is composed of electrodes as well as resistors or dielectrics that contact said electrodes, a nickel plate layer and a solder plate layer laid down, in that order, on the surfaces of external terminal areas of said electrodes.

28. (Previously Presented) The surface mount composite electronic component according to claim 25, wherein one surface of the insulating substrate is substantially perpendicular to an adjacent surface.

29. (Previously Presented) The surface mount composite electronic component according to claim 25, having an area in which no electrodes are present on an edge portion of the surface of the insulating substrate on which said external terminals are present, disposed perpendicular to a straight line connecting a pair of external terminals electrically connected to one circuit element.

30. (Previously Presented) The surface mount composite electronic component according to claim 25, having an area in which the electrodes and the resistor overlap and contact each other on the surface of the insulating substrate, the resistor disposed on the insulating substrate in said area, and further, the electrodes laid on the resistor.

31. (Previously Presented) The surface mount composite electronic component according to claim 25, wherein a relation between an insulating substrate dimension (L) in a direction of flow of electric current of the circuit element of the insulating substrate surface on which circuit elements are formed, an insulating substrate dimension (T) perpendicular to L, and a distance (W) between surfaces of the insulating substrate on which the circuit elements are formed is $L \geq W > T$.

32. (Previously Presented) The surface mount composite electronic component according to claim 25, wherein the electrodes that also function as external terminals are also present on a surface of the insulating substrate adjacent to the surface of the insulating substrate on which the circuit elements are present.

33. (Cancelled)

34. (Cancelled)